

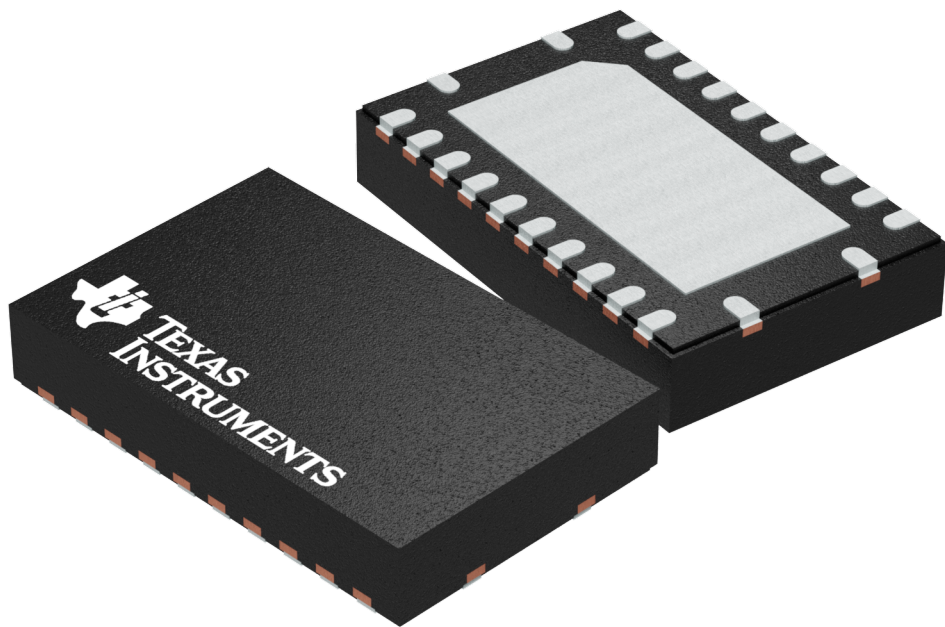
GENERIC PACKAGE VIEW

RGY 24

VQFN - 1 mm max height

5.5 x 3.5 mm, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4203539-5/J

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